

Electronic Patent Application Fee Transmittal

Application Number:	10765931			
Filing Date:	29-Jan-2004			
Title of Invention:	Solder deposition method and solder bump forming method			
First Named Inventor/Applicant Name:	Youichi Kukimoto			
Filer:	Keiko Karen Takagi/Shannon Shenton`			
Attorney Docket Number:	Q79041			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	5	50	250
Independent claims in excess of 3	1201	2	210	420
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120
Miscellaneous:				
Total in USD (\$)				790